

SGM8631/2/3

6MHz, Rail-to-Rail I/O

CMOS Operational Amplifiers

PRODUCT DESCRIPTION

The SGM8631 (single), SGM8632 (dual) and SGM8633 (single with shutdown) are low noise, low voltage, and low power operational amplifiers that can be designed into a wide range of applications. The SGM8631/2/3 have a high gain-bandwidth product of 6MHz and a slew rate of 3.7V/ μ s. The SGM8633 has a power-down disable feature that reduces the supply current to less than 1 μ A.

The SGM8631/2/3 are designed to provide optimal performance in low voltage and low noise systems. They provide rail-to-rail output swing into heavy loads. The input common mode voltage range includes ground, and the maximum input offset voltage is 3.5mV for SGM8631/2/3. They are specified over the extended industrial temperature range (-40°C to +125°C). The operating supply range is from 2V to 5.5V.

The SGM8631 single is available in Green SC70-5, SOT-23-5 and SOIC-8 packages. The SGM8632 dual is available in Green SOIC-8 and MSOP-8 packages. The SGM8633 single with shutdown is available in Green SOT-23-6 and SOIC-8 packages.

FEATURES

- **Rail-to-Rail Input and Output**
3.5mV Maximum V_{OS}
- **High Gain-Bandwidth Product: 6MHz**
- **High Slew Rate: 3.7V/ μ s**
- **Settling Time to 0.1% with 2V Step: 0.5 μ s**
- **Overload Recovery Time: 0.9 μ s**
- **Low Noise: 13nV/ $\sqrt{\text{Hz}}$ at 1kHz**
- **Supply Voltage Range: 2V to 5.5V**
- **Input Voltage Range: -0.1V to +5.6V with $V_S = 5.5V$**
- **Low Supply Current**
SGM8631/3: 570 μ A (TYP)
SGM8632: 480 μ A/Amplifier (TYP)
Less than 1 μ A Shutdown Current for SGM8633
- **Small Packaging**
SGM8631 Available in Green SC70-5, SOT-23-5 and SOIC-8
SGM8632 Available in Green MSOP-8 and SOIC-8
SGM8633 Available in Green SOT-23-6 and SOIC-8

APPLICATIONS

Sensors
Audio
Active Filters
A/D Converters
Communications
Test Equipment
Cellular and Cordless Phones
Laptops and PDAs
Photodiode Amplification
Battery-Powered Instrumentation

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM8631	SC70-5	-40°C to +125°C	SGM8631XC5/TR	8631	Tape and Reel, 3000
	SOT-23-5	-40°C to +125°C	SGM8631XN5/TR	8631	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM8631XS/TR	SGM8631XS XXXXX	Tape and Reel, 2500
SGM8632	MSOP-8	-40°C to +125°C	SGM8632XMS/TR	SGM8632 XMS XXXXX	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM8632XS/TR	SGM8632XS XXXXX	Tape and Reel, 2500
SGM8633	SOT-23-6	-40°C to +125°C	SGM8633XN6/TR	8633	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM8633XS/TR	SGM8633XS XXXXX	Tape and Reel, 2500

NOTE: XXXXX = Date Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $+V_S$ to $-V_S$ 6V
 Input Common Mode Voltage Range
 ($-V_S$) - 0.3V to $(+V_S) + 0.3V$
 Storage Temperature Range-65°C to +150°C
 Junction Temperature+150°C
 Package Thermal Resistance @ $T_A = 25^\circ\text{C}$
 SC70-5, θ_{JA} 333°C/W
 SOT-23-5, θ_{JA} 190°C/W
 SOT-23-6, θ_{JA} 190°C/W
 SOIC-8, θ_{JA} 125°C/W
 MSOP-8, θ_{JA} 216°C/W
 Lead Temperature (Soldering 10sec)
+260°C
 ESD Susceptibility
 HBM (SGM8631/2) 8000V
 HBM (SGM8633) 4000V
 MM 400V
 CDM 1000V

RECOMMENDED OPERATING CONDITIONS

Operating Temperature Range-40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

ESD SENSITIVITY CAUTION

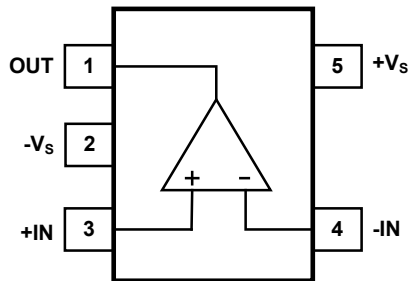
This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.

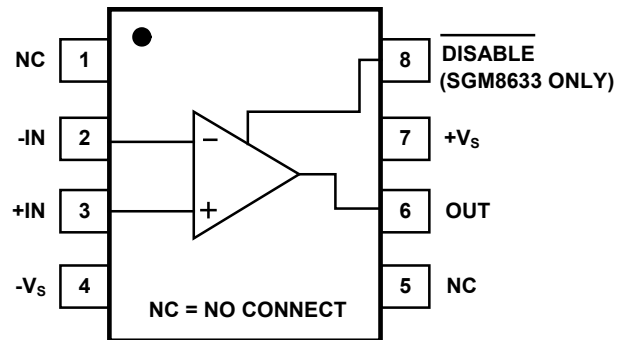
PIN CONFIGURATIONS

SGM8631 (TOP VIEW)



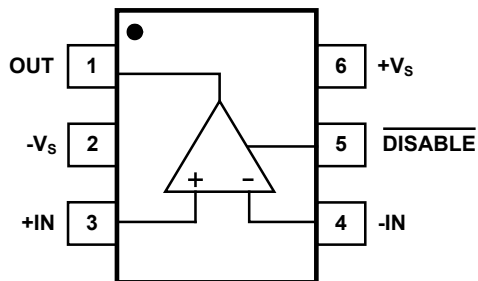
SC70-5/SOT-23-5

SGM8631/8633 (TOP VIEW)



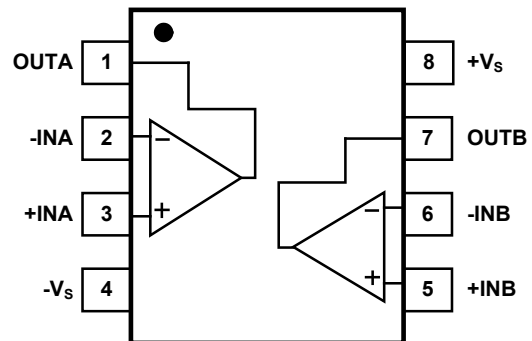
SOIC-8

SGM8633 (TOP VIEW)



SOT-23-6

SGM8632 (TOP VIEW)



SOIC-8/MSOP-8

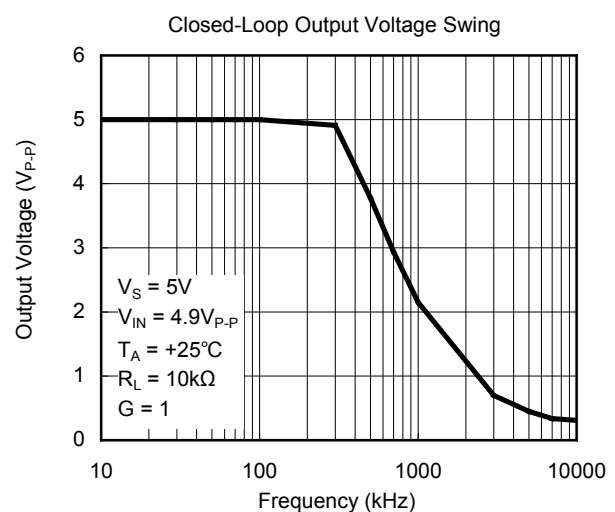
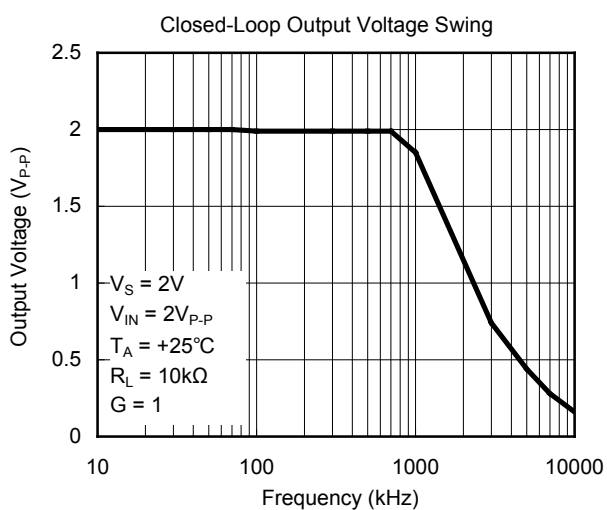
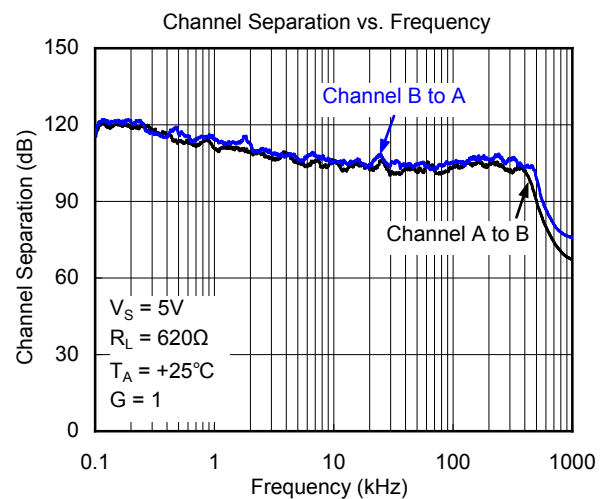
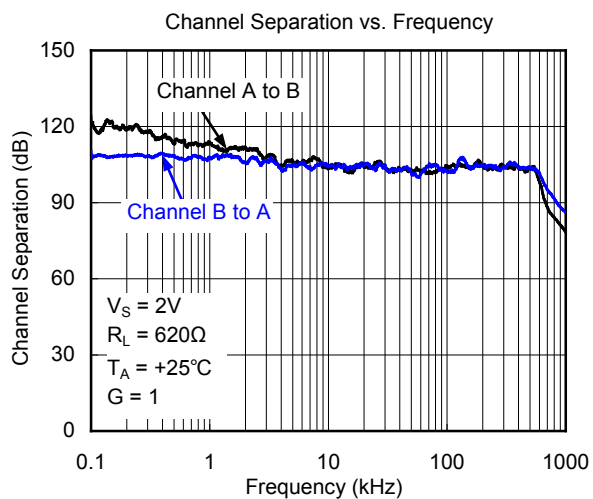
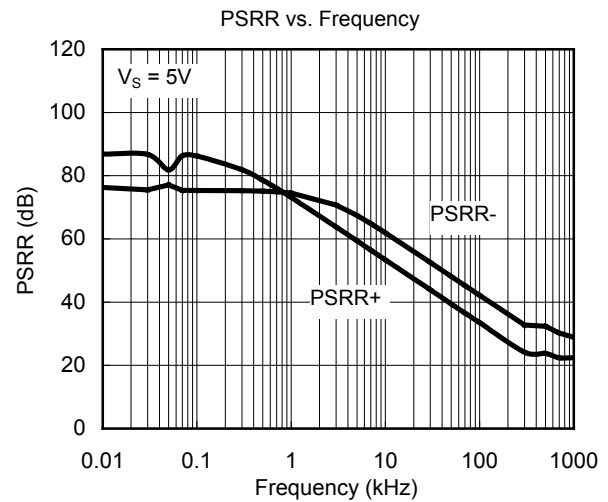
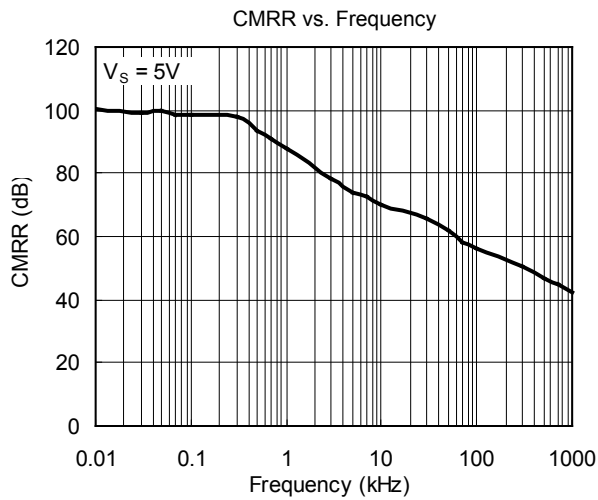
ELECTRICAL CHARACTERISTICS

(At $T_A = +25^\circ\text{C}$, $V_S = +5\text{V}$, $V_{CM} = V_S/2$, $R_L = 600\Omega$, unless otherwise noted.)

PARAMETER		CONDITIONS	SGM8631/2/3					
			TYP	MIN/MAX OVER TEMPERATURE				
			+25°C	+25°C	-40°C to +85°C	-40°C to +125°C	UNITS	MIN/ MAX
INPUT CHARACTERISTICS								
Input Offset Voltage (V _{OS})			0.9	3.5	3.7	3.8	mV	MAX
Input Bias Current (I _B)			1				pA	TYP
Input Offset Current (I _{OS})			1				pA	TYP
Input Common Mode Voltage Range (V _{CM})		V _S = 5.5V	-0.1 to 5.6				V	TYP
Common Mode Rejection Ratio (CMRR)		V _S = 5.5V, V _{CM} = -0.1V to 4V	84	68	67	66	dB	MIN
		V _S = 5.5V, V _{CM} = -0.1V to 5.6V	76				dB	MIN
Open-Loop Voltage Gain (A _{OL})		R _L = 600Ω, V _O = 0.15V to 4.85V	86	79	73	69	dB	MIN
		R _L = 10kΩ, V _O = 0.05V to 4.95V	103				dB	MIN
Input Offset Voltage Drift (ΔV _{OS} /ΔT)			2.4				μV/°C	TYP
OUTPUT CHARACTERISTICS								
Output Voltage Swing from Rail		R _L = 600Ω	0.079				V	TYP
		R _L = 10kΩ	0.007				V	TYP
Output Current (I _{OUT})			58	40	30	26	mA	MIN
Closed-Loop Output Impedance		f = 200kHz, G = 1	5.4				Ω	TYP
POWER-DOWN DISABLE (SGM8633 ONLY)								
Turn-On Time			1.3				μs	TYP
Turn-Off Time			0.4				μs	TYP
DISABLE Voltage-Off				0.8			V	MAX
DISABLE Voltage-On				2			V	MIN
POWER SUPPLY								
Operating Voltage Range			2	2	2	2	V	MIN
			5.5	5.5	5.5	5.5	V	MAX
Power Supply Rejection Ratio (PSRR)		V _S = 2V to 5.5V, V _{CM} = (-V _S) + 0.5V	84	69	68	67	dB	MIN
Quiescent Current/ Amplifier (I _Q)	SGM8632	I _{OUT} = 0	480	620	720	790	μA	MAX
	SGM8631/3	I _{OUT} = 0	570	720	820	880	μA	MAX
Supply Current when Disabled (SGM8633 only)			0.5	8	9	10	μA	MAX
DYNAMIC PERFORMANCE								
Gain-Bandwidth Product (GBP)			6				MHz	TYP
Phase Margin (φ _O)			63				°	TYP
Full Power Bandwidth (BW _P)		<1% distortion	250				kHz	TYP
Slew Rate (SR)		G=1, 2V output step	3.7				V/μs	TYP
Settling Time to 0.1% (t _S)		G=1, 2V output step	0.5				μs	TYP
Overload Recovery Time		V _{IN} × Gain = V _S	0.9				μs	TYP
NOISE PERFORMANCE								
Voltage Noise Density (e _n)		f = 1kHz	13				nV/√Hz	TYP

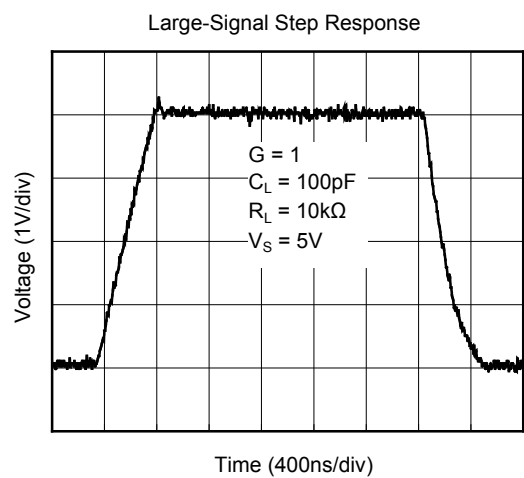
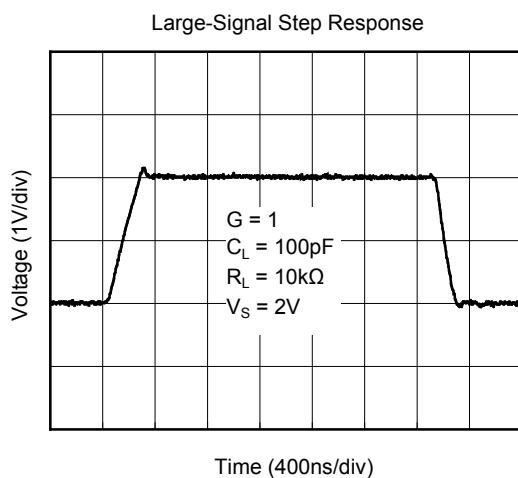
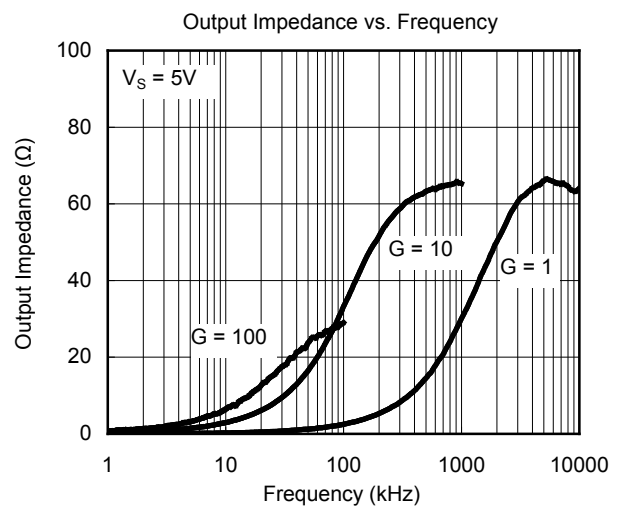
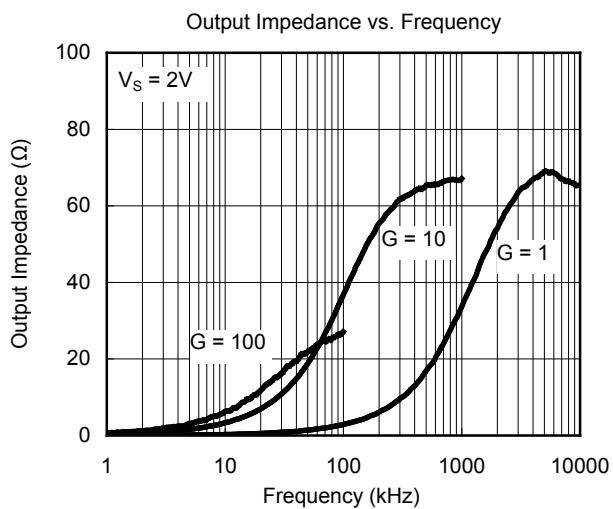
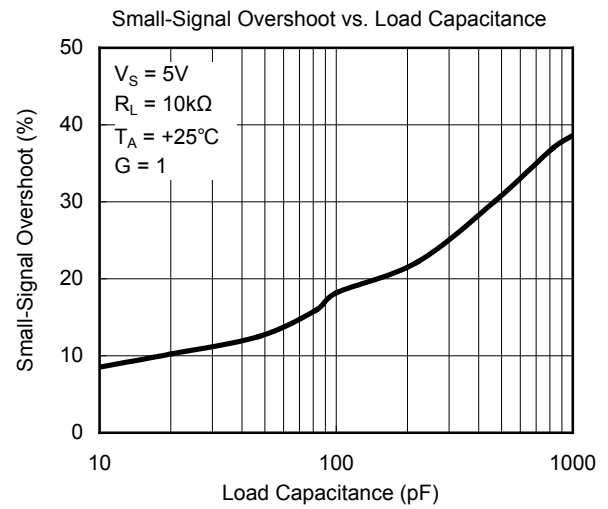
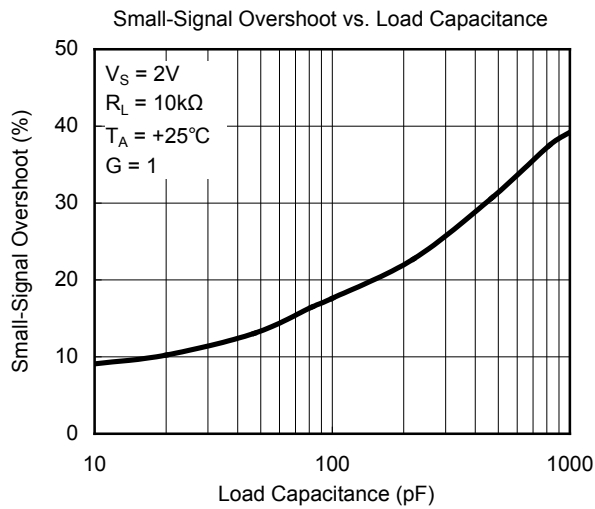
TYPICAL PERFORMANCE CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{CM} = V_S/2$, $R_L = 600\Omega$, unless otherwise noted.



TYPICAL PERFORMANCE CHARACTERISTICS

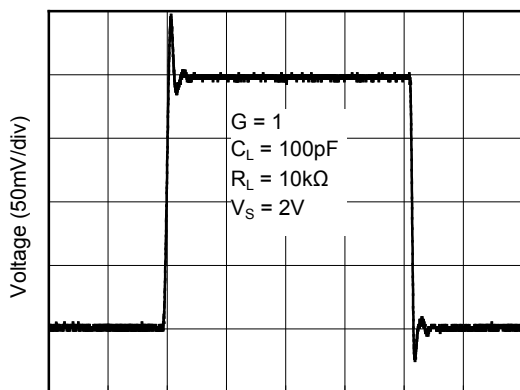
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TYPICAL PERFORMANCE CHARACTERISTICS

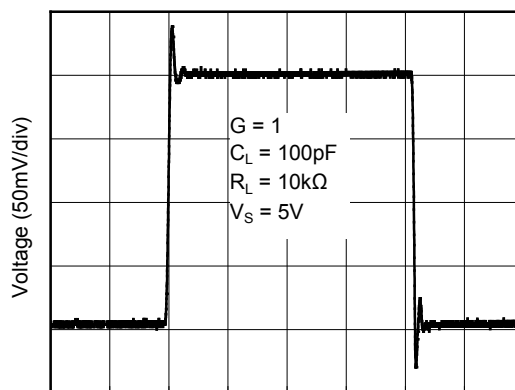
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Small-Signal Step Response



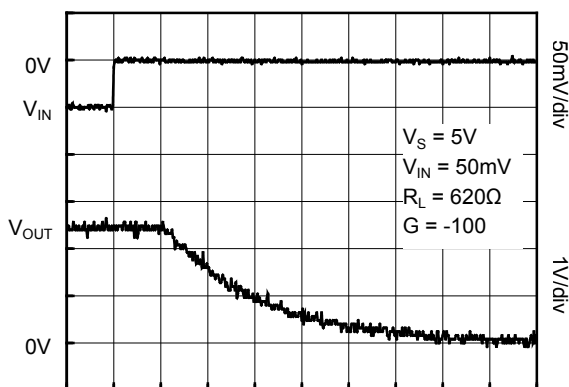
Time (1μs/div)

Small-Signal Step Response



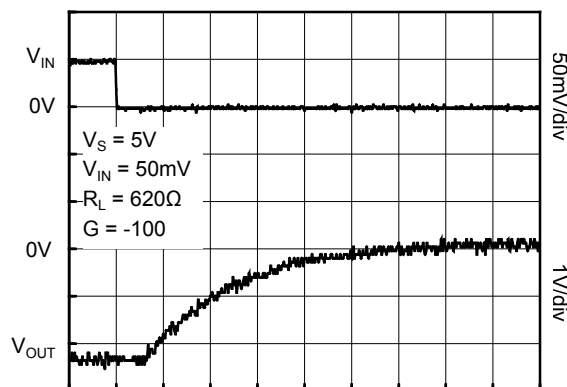
Time (1μs/div)

Positive overload Recovery



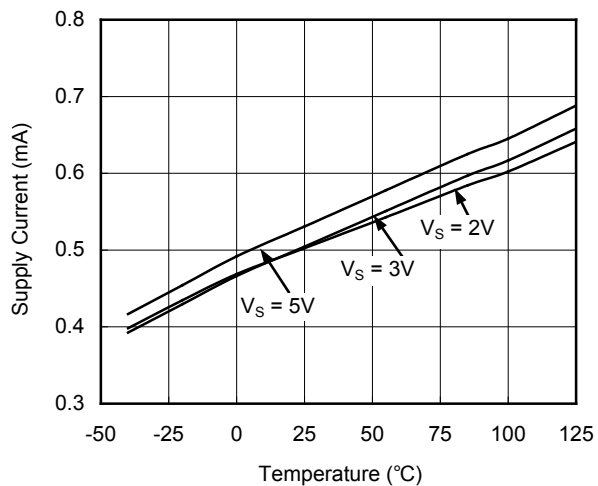
Time (1μs/div)

Negative Overload Recovery

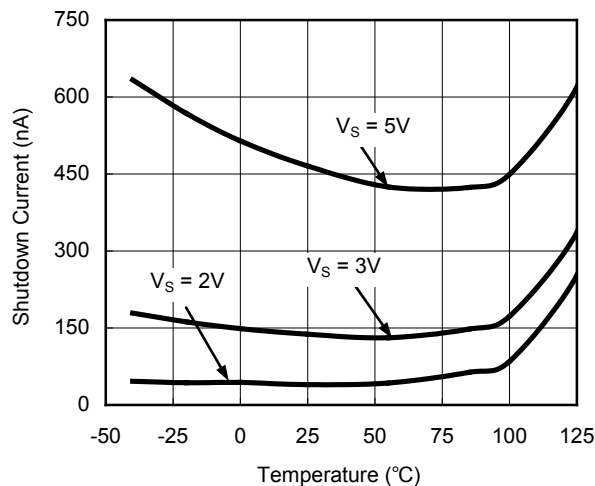


Time (1μs/div)

Supply Current vs. Temperature



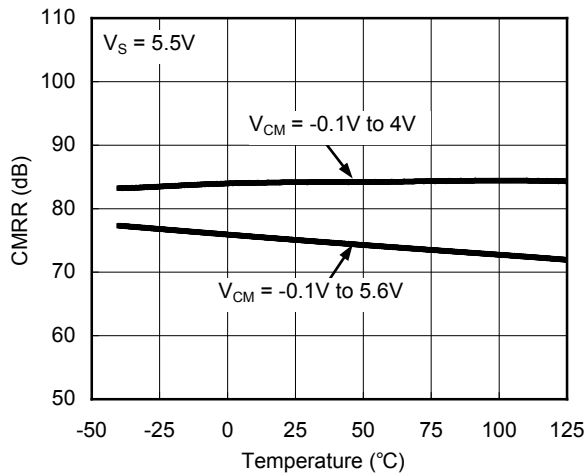
Shutdown Current vs. Temperature



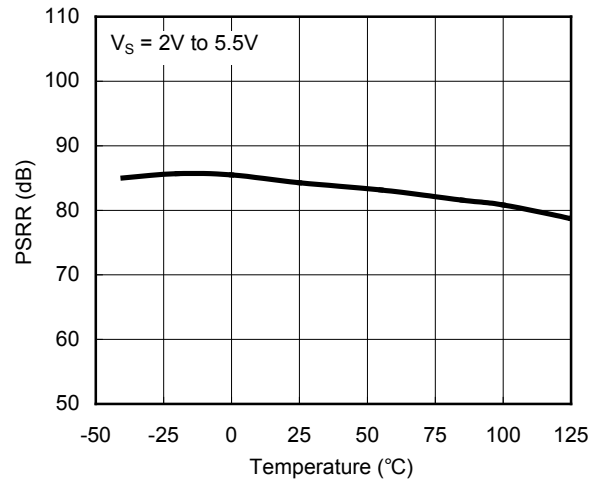
TYPICAL PERFORMANCE CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{CM} = V_S/2$, $R_L = 600\Omega$, unless otherwise noted.

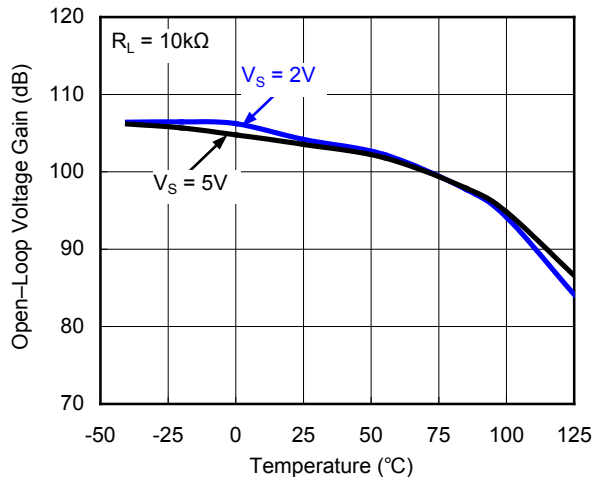
CMRR vs. Temperature



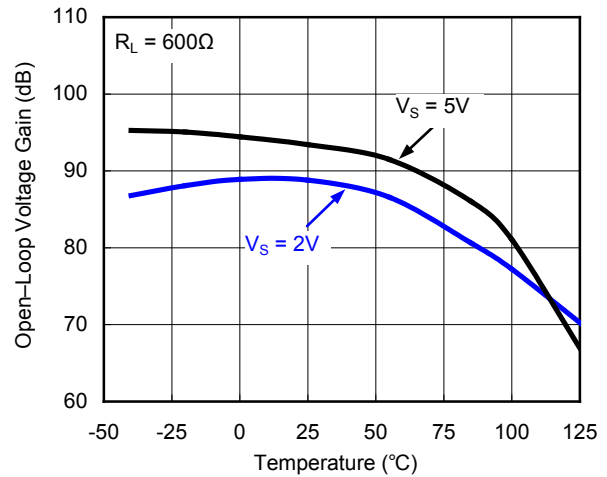
PSRR vs. Temperature



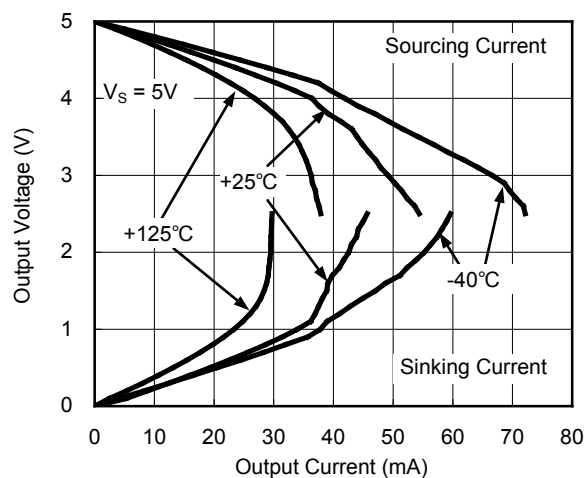
Open-Loop Voltage Gain vs. Temperature



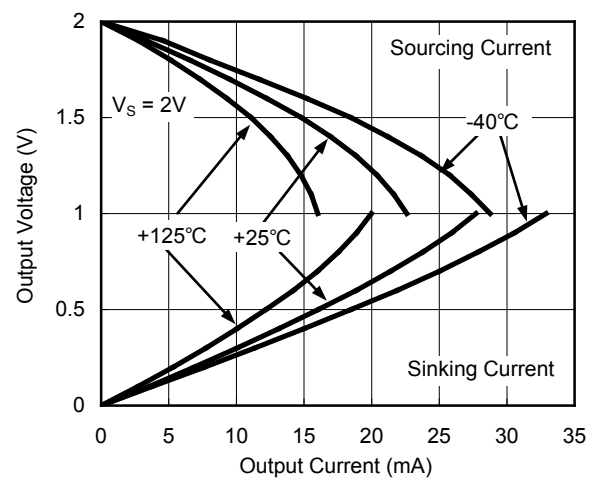
Open-Loop Voltage Gain vs. Temperature



Output Voltage Swing vs. Output Current

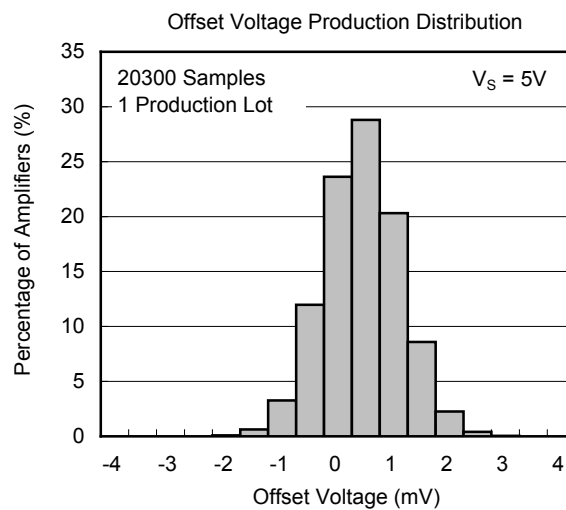
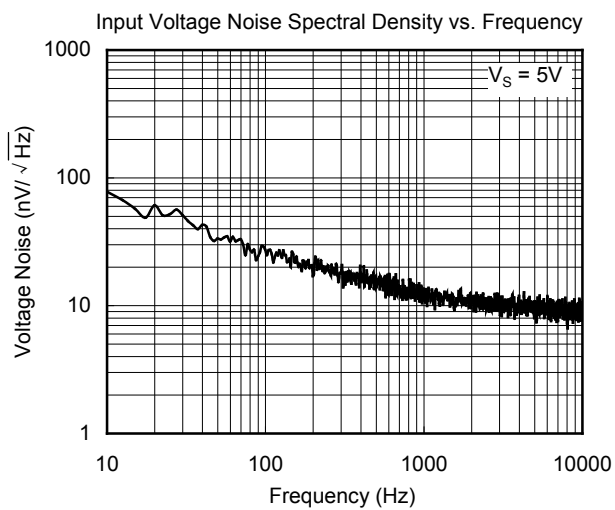


Output Voltage Swing vs. Output Current



TYPICAL PERFORMANCE CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{CM} = V_S/2$, $R_L = 600\Omega$, unless otherwise noted.



APPLICATION NOTES

Driving Capacitive Loads

The SGM8631/2/3 can directly drive 1000pF in unity-gain without oscillation. The unity-gain follower (buffer) is the most sensitive configuration to capacitive loading. Direct capacitive loading reduces the phase margin of amplifiers and this results in ringing or even oscillation. Applications that require greater capacitive driving capability should use an isolation resistor between the output and the capacitive load like the circuit in Figure 1. The isolation resistor R_{ISO} and the load capacitor C_L form a zero to increase stability. The bigger the R_{ISO} resistor value, the more stable V_{OUT} will be. Note that this method results in a loss of gain accuracy because R_{ISO} forms a voltage divider with the R_{LOAD} .

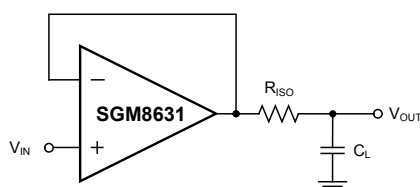


Figure 1. Indirectly Driving Heavy Capacitive Load

An improved circuit is shown in Figure 2. It provides DC accuracy as well as AC stability. R_F provides the DC accuracy by connecting the inverting input with the output. C_F and R_{ISO} serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving phase margin in the overall feedback loop.

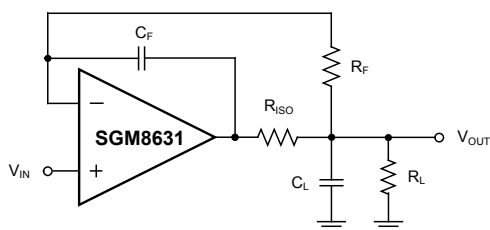


Figure 2. Indirectly Driving Heavy Capacitive Load with DC Accuracy

For non-buffer configuration, there are two other ways to increase the phase margin: (a) by increasing the amplifier's closed-loop gain or (b) by placing a capacitor in parallel with the feedback resistor to counteract the parasitic capacitance associated with inverting node.

Power-Supply Bypassing and Layout

The SGM8631/2/3 family operates from either a single +2V to +5.5V supply or dual $\pm 1V$ to $\pm 2.75V$ supplies. For single-supply operation, bypass the power supply + V_S with a 0.1 μF ceramic capacitor which should be placed close to the + V_S pin. For dual-supply operation, both the + V_S and the - V_S supplies should be bypassed to ground with separate 0.1 μF ceramic capacitors. 2.2 μF tantalum capacitor can be added for better performance.

Good PC board layout techniques optimize performance by decreasing the amount of stray capacitance at the op amp's inputs and output. To decrease stray capacitance, minimize trace lengths and widths by placing external components as close to the device as possible. Use surface-mount components whenever possible.

For the operational amplifier, soldering the part to the board directly is strongly recommended. Try to keep the high frequency current loop area small to minimize the EMI (electromagnetic interfacing).

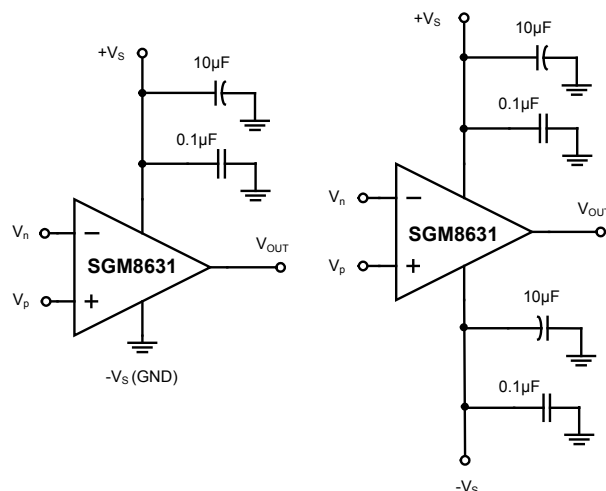


Figure 3. Amplifier with Bypass Capacitors

Grounding

A ground plane layer is important for SGM8631/2/3 circuit design. The length of the current path in an inductive ground return will create an unwanted voltage noise. Broad ground plane areas will reduce the parasitic inductance.

Input-to-Output Coupling

To minimize capacitive coupling, the input and output signal traces should not be in parallel. This helps reduce unwanted positive feedback.

TYPICAL APPLICATION CIRCUITS

Differential Amplifier

The circuit shown in Figure 4 performs the difference function. If the resistor ratios are equal ($R_4/R_3 = R_2/R_1$), then $V_{OUT} = (V_p - V_n) \times R_2/R_1 + V_{REF}$.

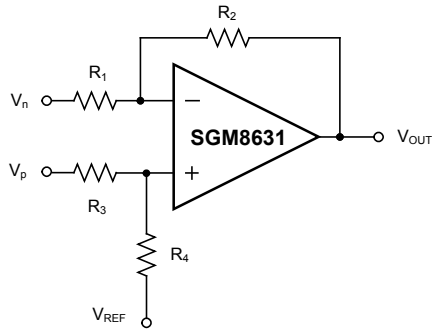


Figure 4. Differential Amplifier

Instrumentation Amplifier

The circuit in Figure 5 performs the same function as that in Figure 4 but with a high input impedance.

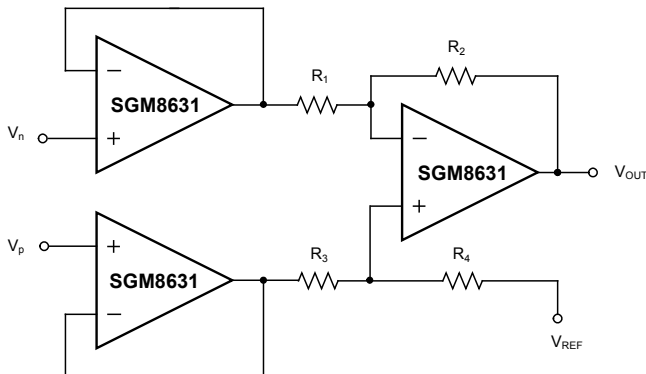


Figure 5. Instrumentation Amplifier

Low-Pass Active Filter

The low-pass filter shown in Figure 6 has a DC gain of $(-R_2/R_1)$ and the -3dB corner frequency is $1/2\pi R_2 C$. Make sure the filter bandwidth is within the bandwidth of the amplifier. The large values of feedback resistors can couple with parasitic capacitance and cause undesired effects such as ringing or oscillation in high-speed amplifiers. Keep resistor values as low as possible and consistent with output loading consideration.

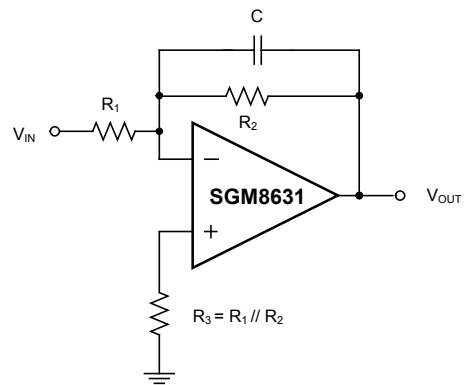
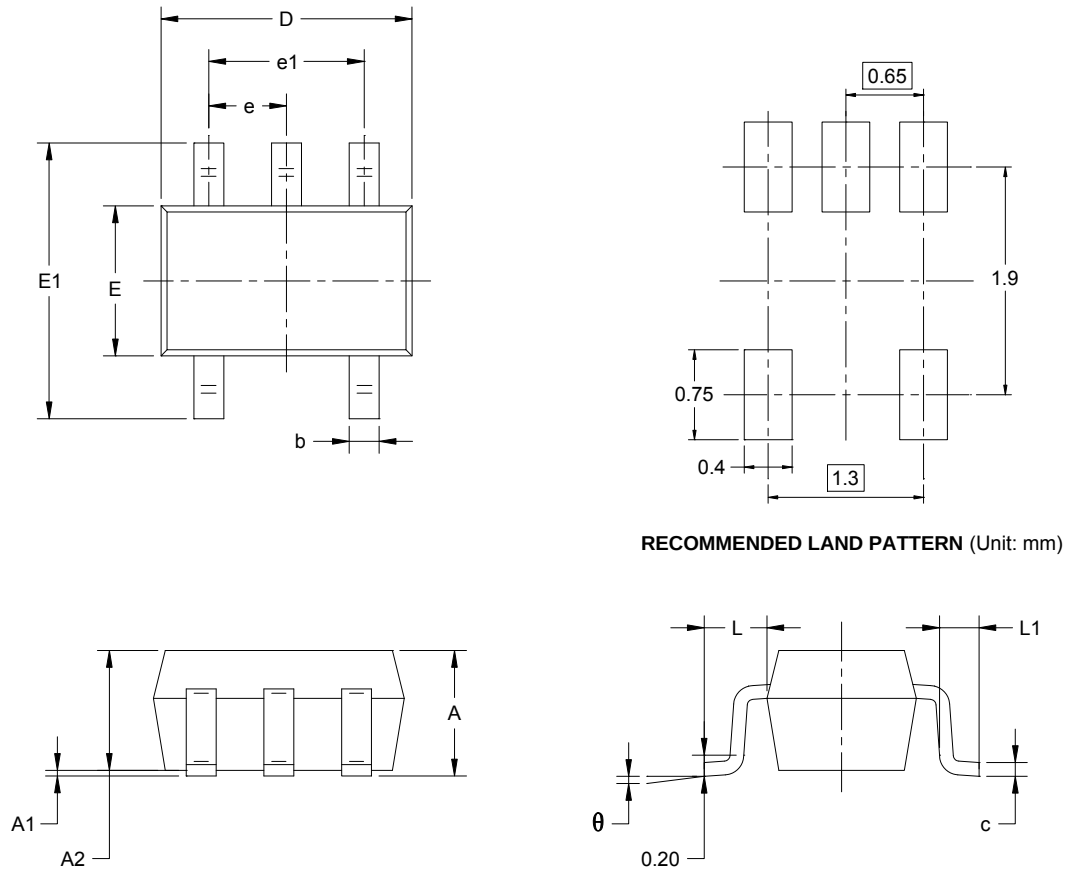


Figure 6. Low-Pass Active Filter

PACKAGE OUTLINE DIMENSIONS

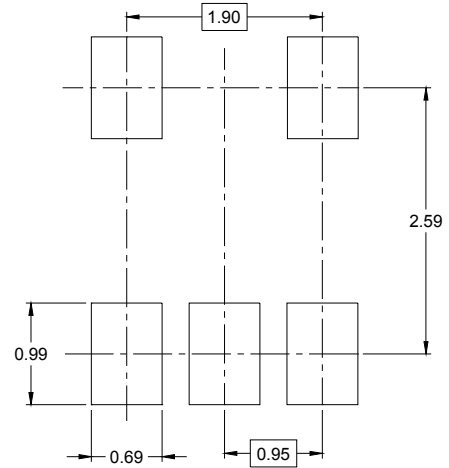
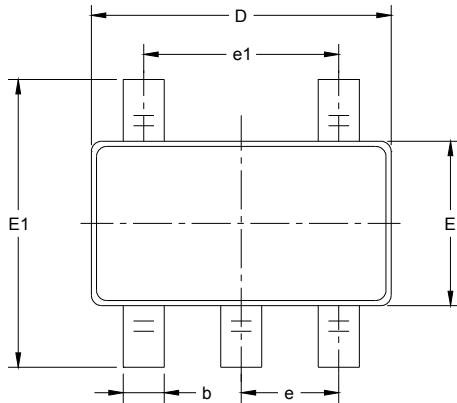
SC70-5



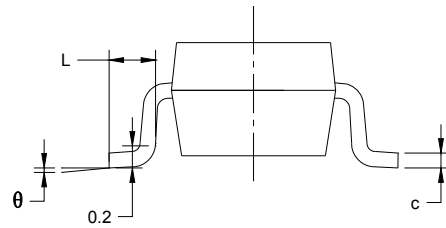
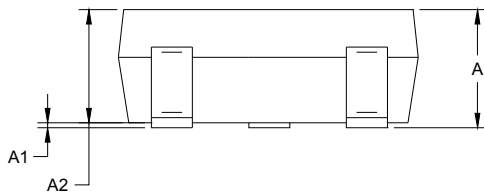
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.65 TYP		0.026 TYP	
e1	1.300 BSC		0.051 BSC	
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

SOT-23-5



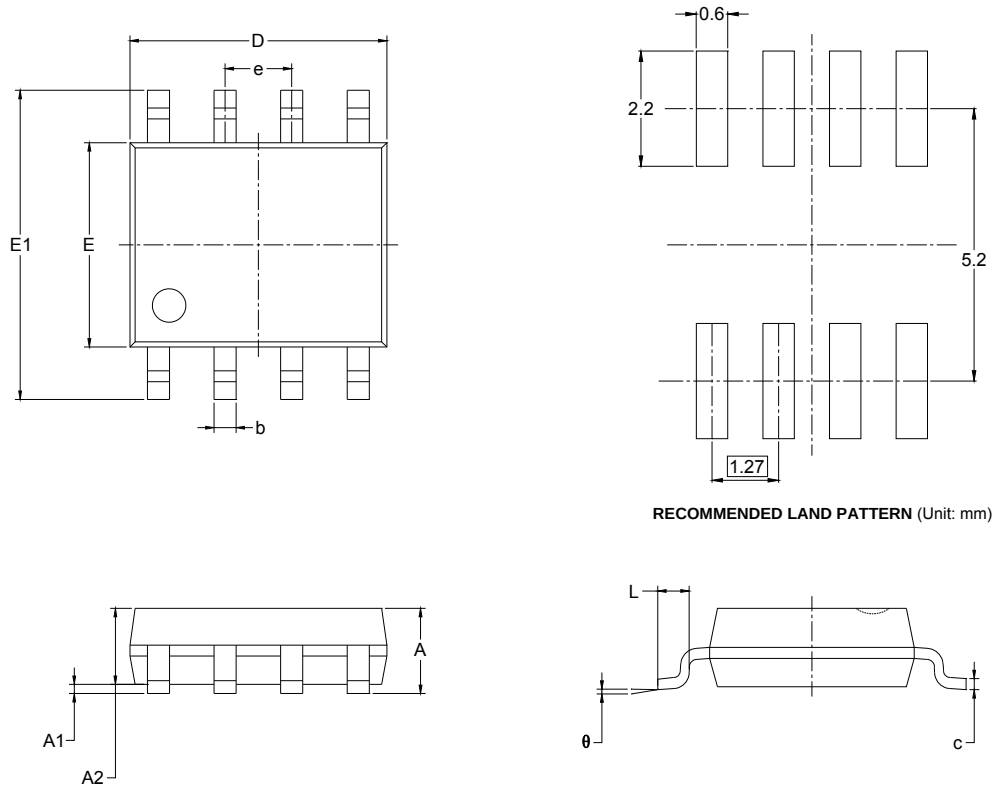
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

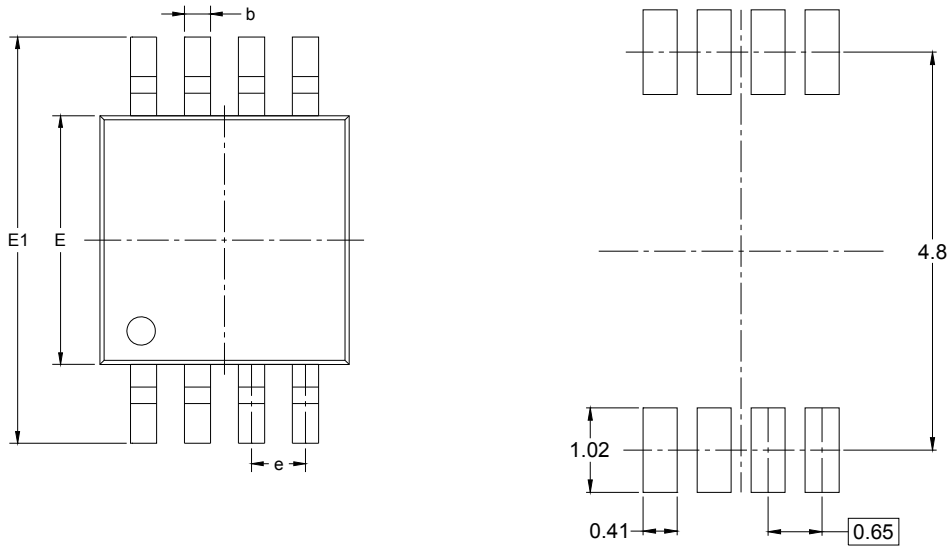
SOIC-8



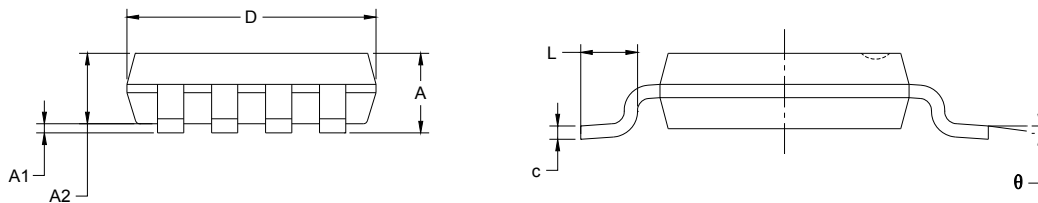
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

MSOP-8



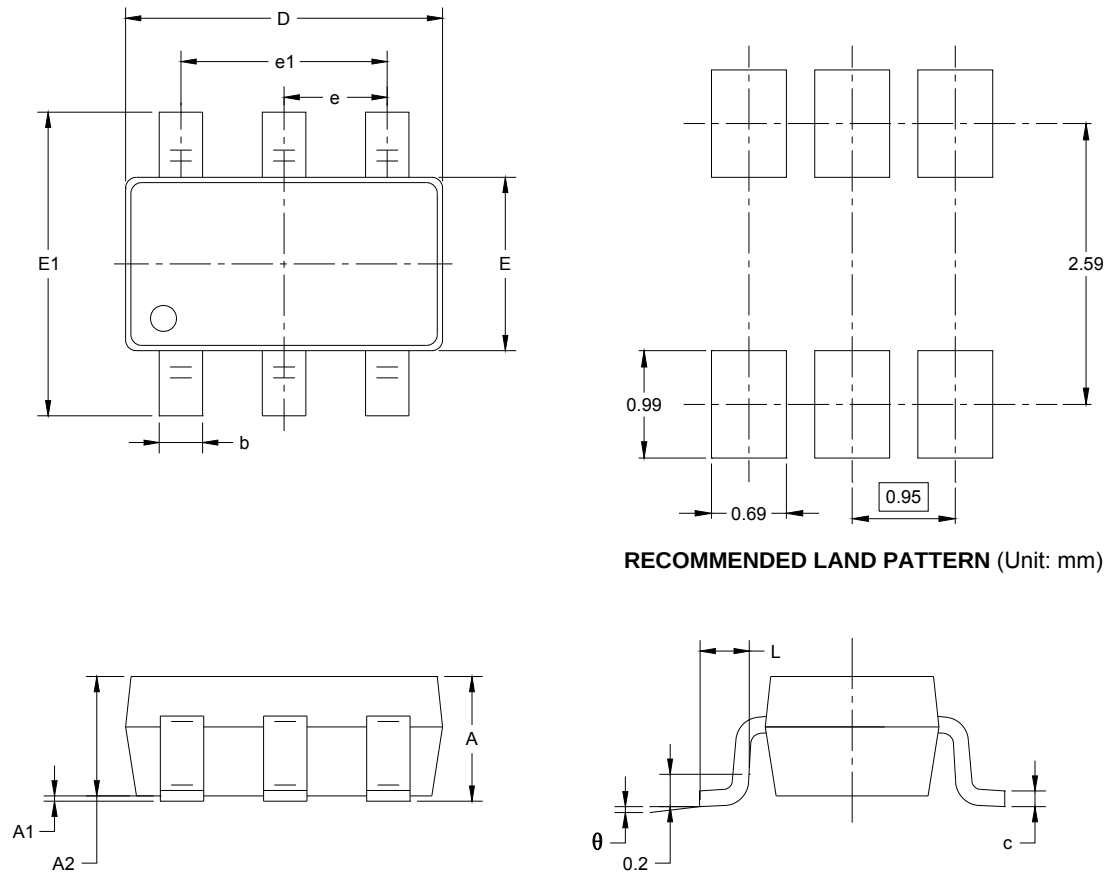
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
e	0.650 BSC		0.026 BSC	
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

PACKAGE OUTLINE DIMENSIONS

SOT-23-6



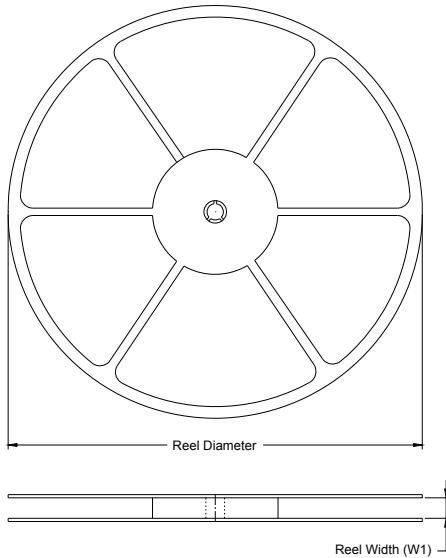
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

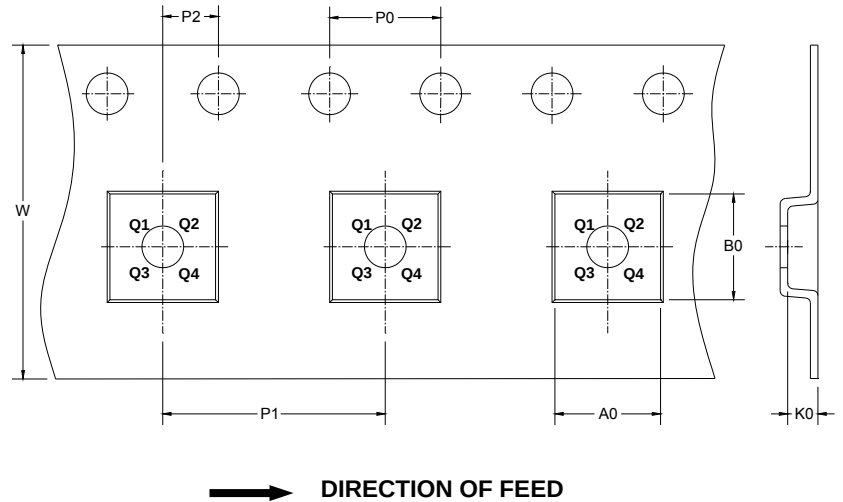
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

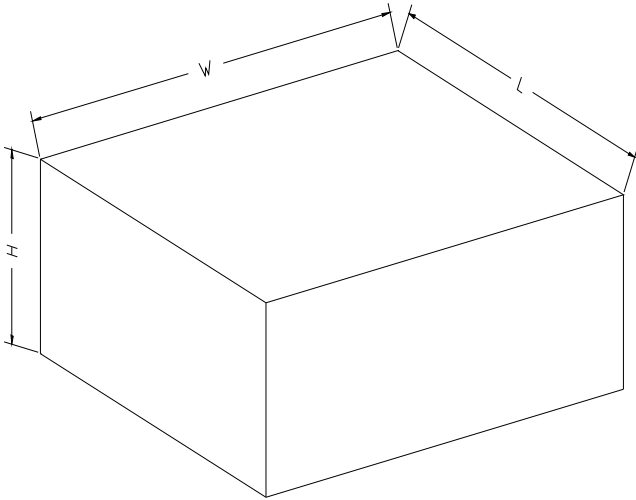
KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SC70-5	7"	9.5	2.25	2.55	1.20	4.0	4.0	2.0	8.0	Q3
SOT-23-5	7"	9.5	3.2	3.2	1.4	4.0	4.0	2.0	8.0	Q3
SOT-23-6	7"	9.5	3.17	3.23	1.37	4.0	4.0	2.0	8.0	Q3
SOIC-8	13"	12.4	6.4	5.4	2.1	4.0	8.0	2.0	12.0	Q1
MSOP-8	13"	12.4	5.2	3.3	1.5	4.0	8.0	2.0	12.0	Q1

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PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5

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